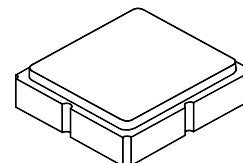


SF2315E-1

**782 MHz
SAW Filter**



SM3030-8

- *Low-loss 782 MHz SAW Filter*
- *Designed for 50 ohm Source/Load*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Moisture Sensitivity Level: 1*

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+25	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

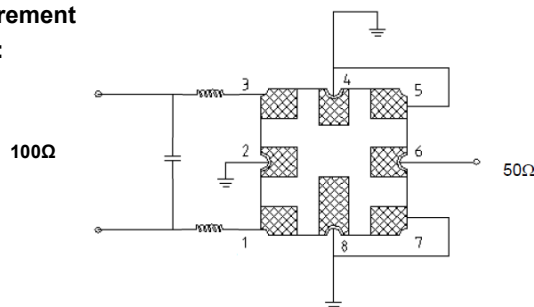
Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			782		MHz
Insertion Loss, 777 to 787 MHz	IL			2.6	3.4	dB
Bandwidth			10	29		MHz
Amplitude Ripple, 777 to 787 MHz				0.3	1.00	dB _{P-P}
Attenuation, Referenced to 0 dB:						dB
300 to 700 MHz			28	46		
728 to 757 MHz			10	40		
880 to 1050 MHz			28	42		
Source Impedance	Z_S			100		Ω
Load Impedance	Z_L			50		Ω
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A82, <u>Y</u> WWS					
Standard Reel Quantity	Reel Size 7 inch					500 Pieces/Reel
	Reel Size 13 inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Input	1,3
Output	6
Case Ground	All others

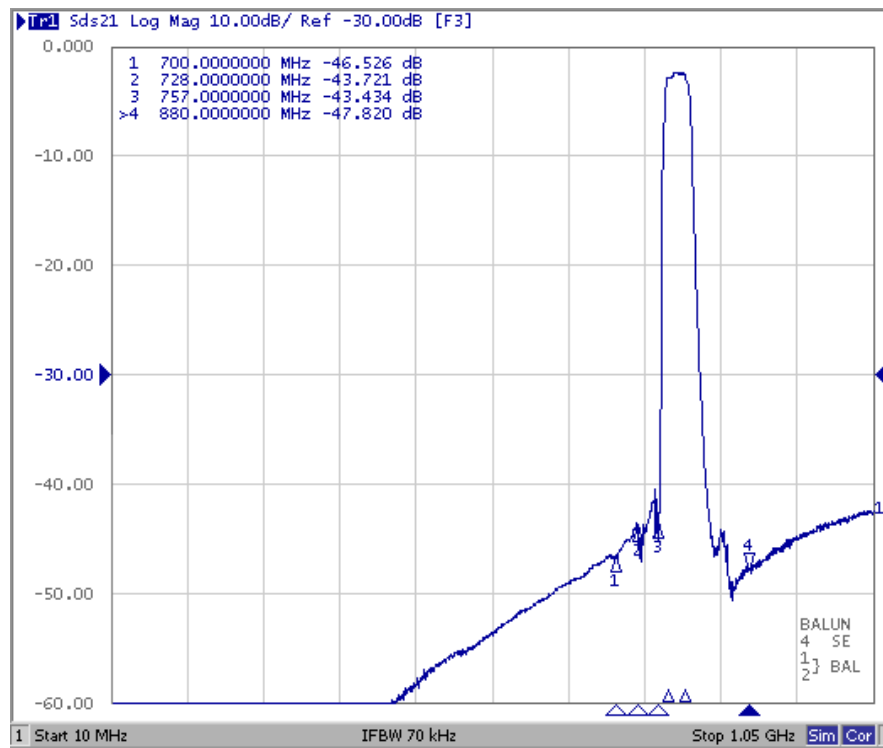
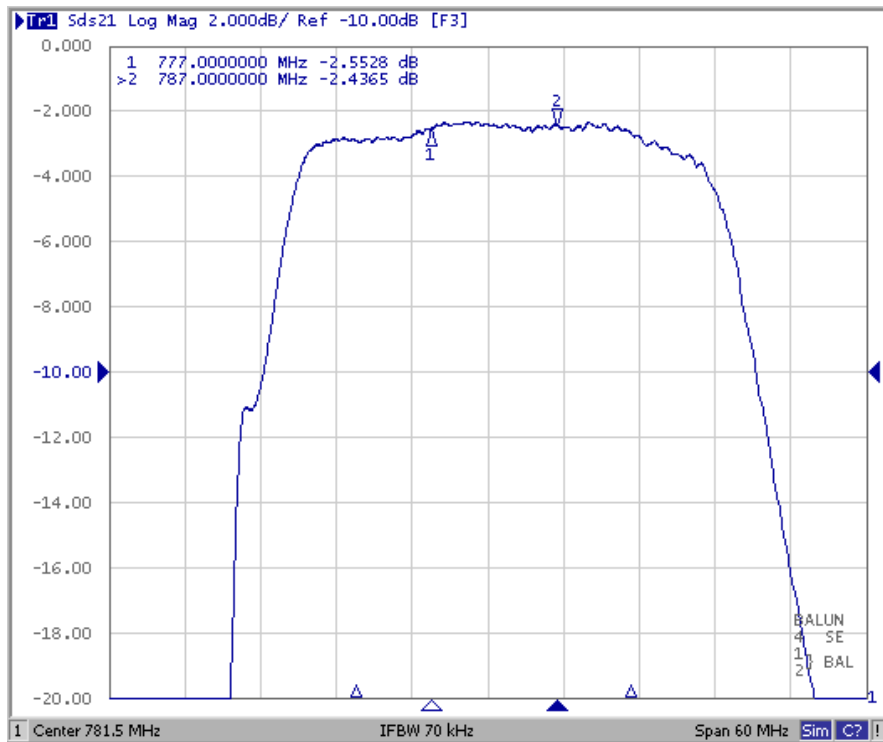
Measurement Circuit:



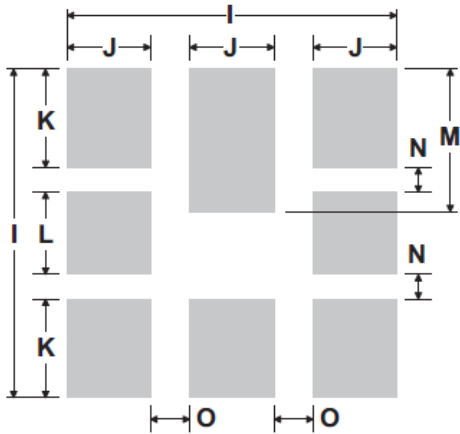
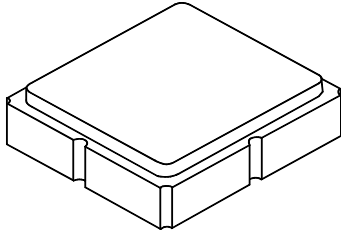
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Filter Response Plots



8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

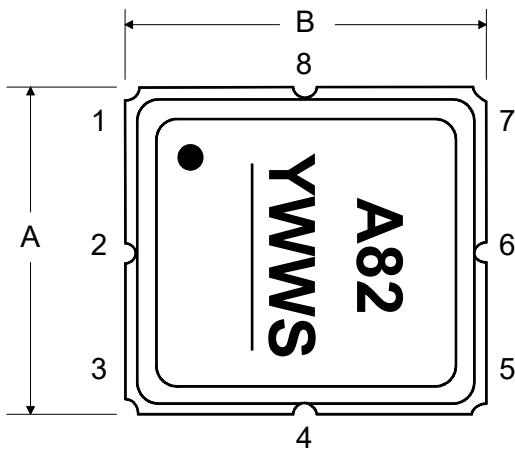
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

TOP VIEW



BOTTOM VIEW

